



## Material Content Data Sheet



<b>Sales Product Name</b>		BSZ019N03LS		<b>Issued</b>		25. January 2018		
<b>MA#</b>		MA001651882						
<b>Package</b>		PG-TSDSON-8-26		<b>Weight*</b>		36.78 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.671	1.82	1.82	18243	18243
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		67	
	non noble metal	zinc	7440-66-6	0.010	0.03		267	
	non noble metal	iron	7439-89-6	0.197	0.53		5349	
wire	non noble metal	copper	7440-50-8	7.988	21.72	22.29	217175	222858
	noble metal	gold	7440-57-5	0.028	0.07	0.07	748	748
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		999
encapsulation	plastics	epoxy resin	-	1.893	5.15		51470	
	inorganic material	silicondioxide	60676-86-0	16.451	44.74	49.99	447236	499705
	leadfinish	non noble metal	tin	7440-31-5	0.395	1.07	1.07	10746
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	552	552
solder	non noble metal	tin	7440-31-5	0.019	0.05		519	
	noble metal	silver	7440-22-4	0.024	0.06		649	
	non noble metal	lead	7439-92-1	0.912	2.48	2.59	24797	25965
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		32	
	non noble metal	zinc	7440-66-6	0.005	0.01		128	
	non noble metal	iron	7439-89-6	0.094	0.26		2555	
heat sink CLIP	non noble metal	copper	7440-50-8	3.816	10.37	10.64	103741	106456
	inorganic material	phosphorus	7723-14-0	0.001	0.00		34	
	non noble metal	zinc	7440-66-6	0.005	0.01		138	
heat sink CLIP	non noble metal	iron	7439-89-6	0.101	0.28		2753	
	non noble metal	copper	7440-50-8	4.112	11.18	11.47	111802	114727
	*deviation	< 10%				Sum in total:	100.00	1000000

### Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com